



0.25 μm BCD PROCESS TECHNOLOGY	
Sample size	12 546
Equivalent device hours	4 877 032
Failure rate in FIT	0.72

Failure rate in FIT is calculated according to JEDEC® standard JESD85, Methods for calculating failure rates in units of FITs, based on accelerated high temperature operating life test results by using an apparent activation energy of 0.7 eV. The junction temperature of the device at use is assumed to be 55 °C. A constant failure rate distribution is assumed. The upper confidence bound of the failure rate is 60 %.